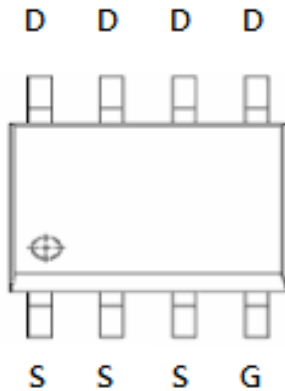


DESCRIPTION

STP4441 is the P-Channel logic enhancement mode power field effect transistor which is produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, notebook power management and other battery powered circuits where high-side switching.

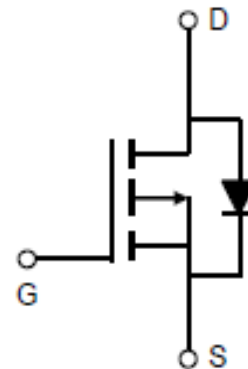
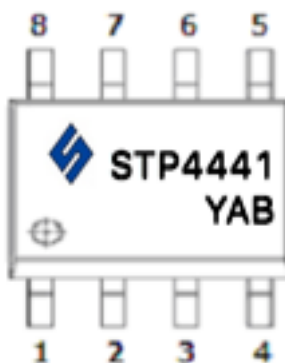
PIN CONFIGURATION SOP-8



FEATURE

- -60V/-10.0A, $R_{DS(ON)} = 55m\Omega$ (Typ.)
@ $V_{GS} = -10V$
- -60V/-5.0A, $R_{DS(ON)} = 73m\Omega$
@ $V_{GS} = -4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOP-8 package design

PART MARKING SOP-8



Y : Year Code
A : Date Code
B : Wafer Code

**STP4441**

P Channel Enhancement Mode MOSFET

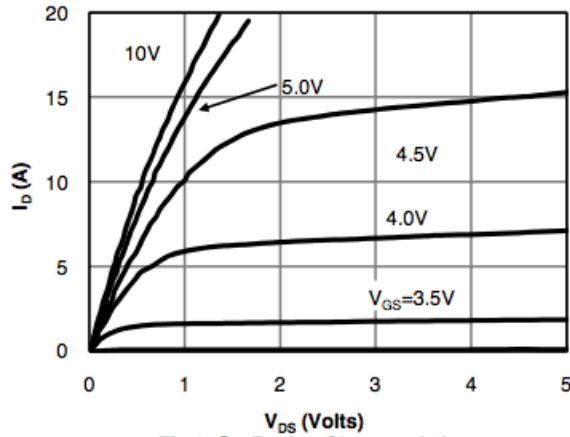
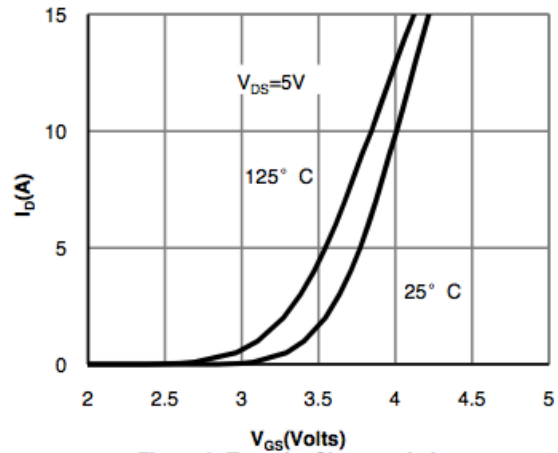
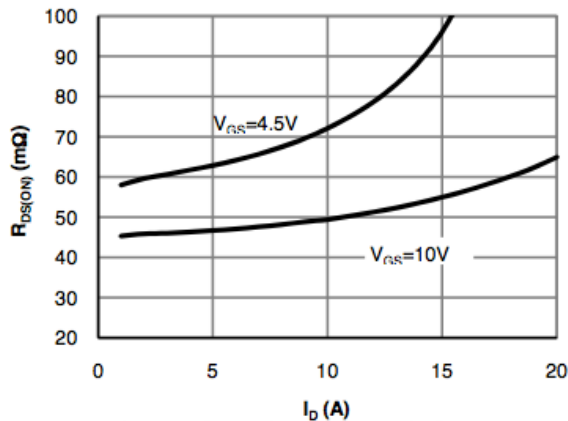
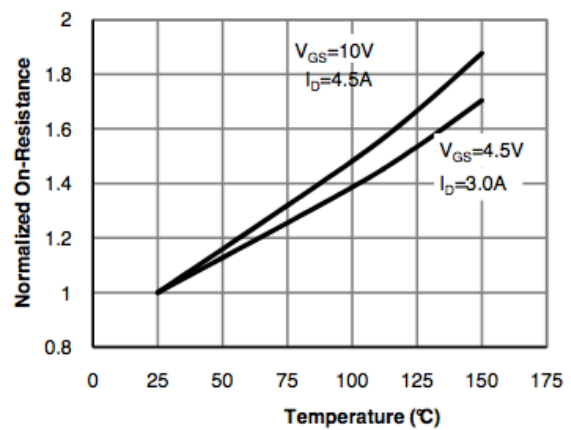
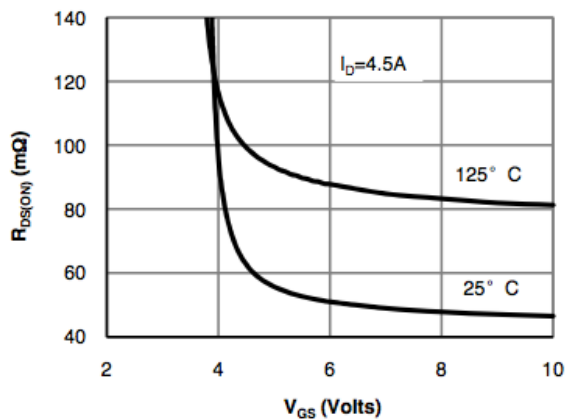
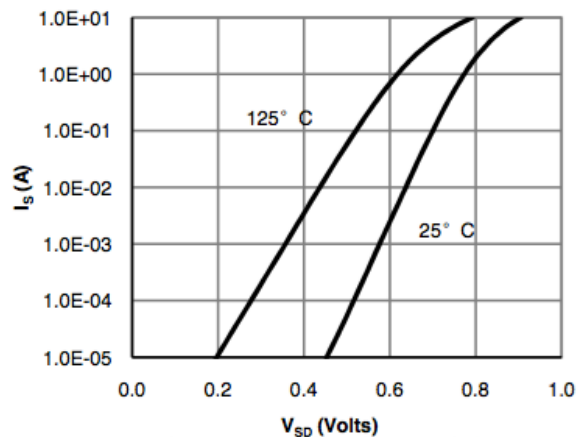
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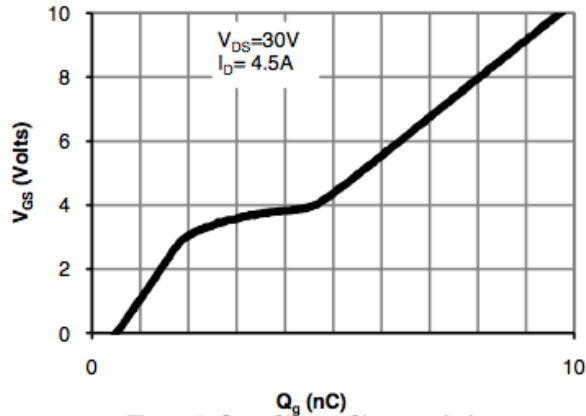
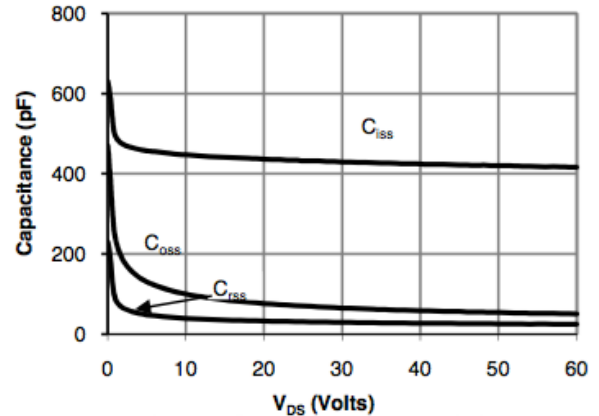
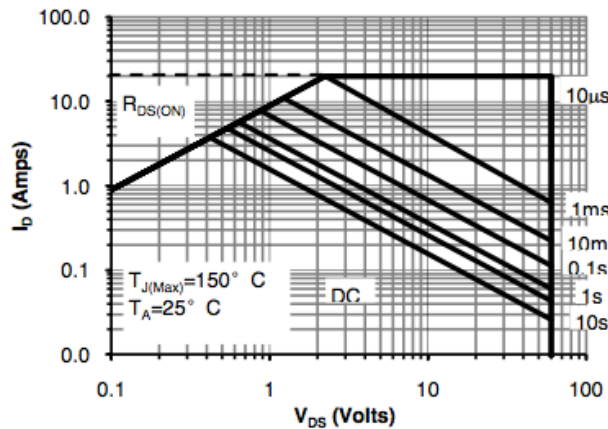
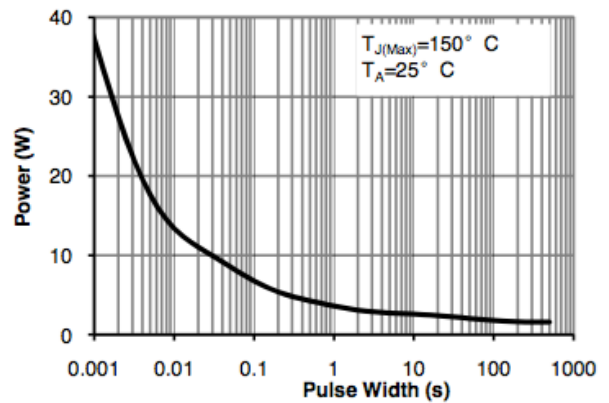
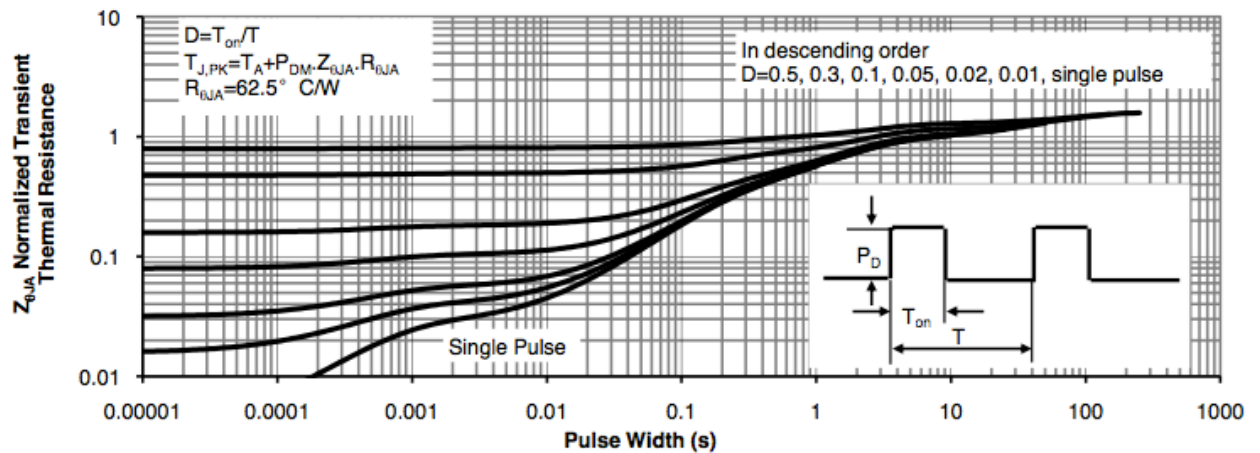
ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)

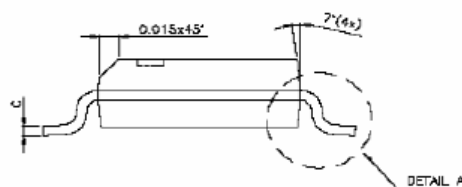
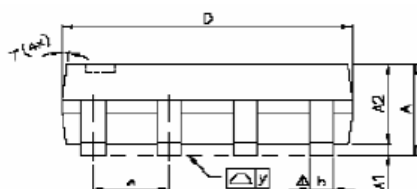
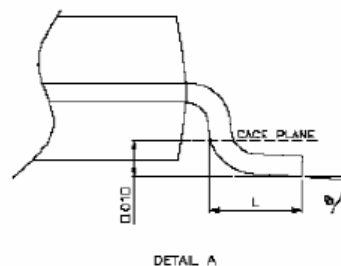
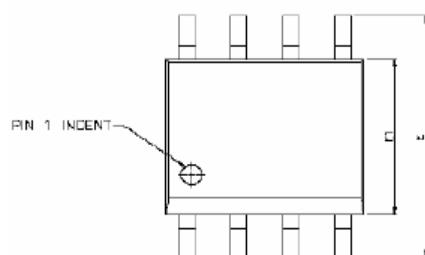
Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V _{DSS}	-60	V
Gate-Source Voltage		V _{GSS}	±20	V
Continuous Drain Current (T _J =150°C)	T _A =25°C T _A =70°C	I _D	-10.0 -4.0	A
Pulsed Drain Current		I _{DM}	-40	A
Continuous Source Current (Diode Conduction)		I _S	-3	A
Power Dissipation	T _A =25°C T _A =70°C	P _D	2.3 1.3	W
Operation Junction Temperature		T _J	-55/150	°C
Storage Temperature Range		T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient		R _{θJA}	70	°C/W

ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V,I _D =-250uA	-60			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250 uA	-0.8		-2.5	V
Gate Leakage Current	I _{GSS}	V _{DS} =0V,V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-48V,V _{GS} =0V			-1	uA
		V _{DS} =-48V,V _{GS} =0V T _J =85℃			-10	
Drain-source On-Resistance	R _{DS(on)}	V _{GS} =-10V, I _D =-10A V _{GS} =-4.5V, I _D =-5A		0.053 0.071	0.060 0.081	Ω
Forward Tran Conductance	g _{fs}	V _{DS} =-5V,I _D =-5.9A		18		S
Diode Forward Voltage	V _{SD}	I _S =-2.3A,V _{GS} =0V		-0.7	-1.0	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =-30V,V _{GS} =-10 I _D ≡-5.0A		47	55	nC
Gate-Source Charge	Q _{gs}			5.8		
Gate-Drain Charge	Q _{gd}			9.3		
Input Capacitance	C _{iss}	V _{DS} =-30V,V _{GS} =0V f=1MHz		2410		pF
Output Capacitance	C _{oss}			179		
Reverse TransferCapacitance	C _{rss}			125		
Turn-On Time	t _{d(on)} tr	V _{DS} =-30V,R _L =4.7Ω V _{GS} =-10V,R _{GEN} =3Ω		9		nS
Turn-Off Time	t _{d(off)} tf			6.2		
				25		
				13.2		

TYPICAL CHARACTERISTICS

Fig 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature

Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics

TYPICAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

Figure 10: Single Pulse Power Rating Junction-Ambient (Note E)

Figure 11: Normalized Maximum Transient Thermal Impedance

SOP-8 PACKAGE OUTLINE


SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10	—	0.25	0.004	—	0.010
A2	—	1.45	—	—	0.057	—
b	0.33	0.41	0.51	0.013	0.016	0.020
c	0.19	0.20	0.25	0.0075	0.008	0.0098
D	4.80	4.85	4.95	0.189	0.191	0.195
E	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e	—	1.27	—	—	0.050	—
L	0.38	0.71	1.27	0.015	0.028	0.050
Δy	—	—	0.076	—	—	0.003
θ	0°	—	8°	0°	—	8°